

Electronic Patent Application Fee Transmittal

Application Number:	10537509			
Filing Date:	30-Nov-2005			
Title of Invention:	Method for cutting semiconductor substrate			
First Named Inventor/Applicant Name:	Fumitsugu Fukuyo			
Filer:	John G. Smith/Towanna Bolling			
Attorney Docket Number:	46884-5388 (211285)			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1615	9	52	468
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				2388